

# **HVU17**

## Variable Capacitance Diode for VCO

REJ03G0079-0400Z

(Previous: ADE-208-021C) Rev.4.00

Sep.17.2003

#### **Features**

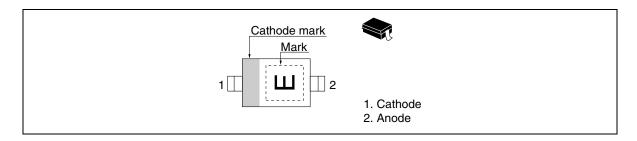
- Good linearity of C-V curve.
- To be usable at low voltage.
- High figure of merit.
- Ultra small Resin Package (URP) is suitable for surface mount design.

#### **Ordering Information**

Type No.	Laser Mark	Package Code
HVU17	E	URP

www.DataSheet4U.com

#### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

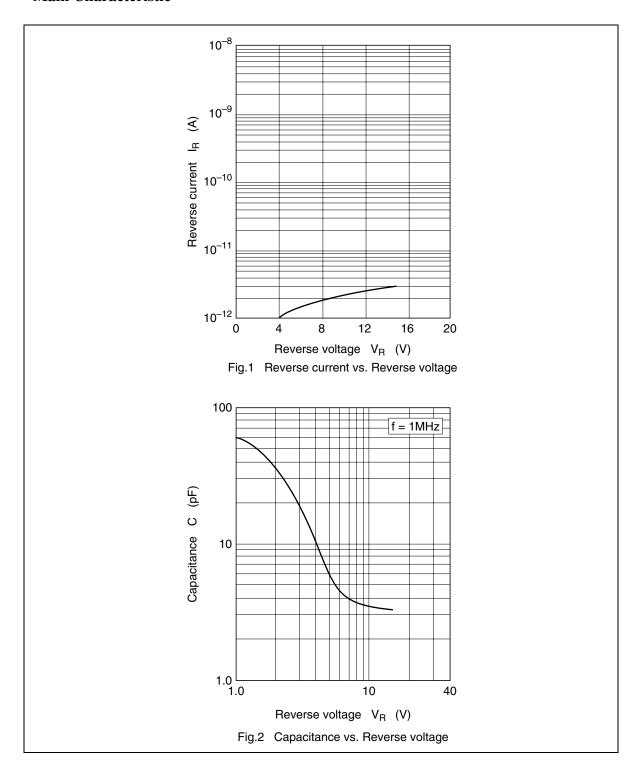
#### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

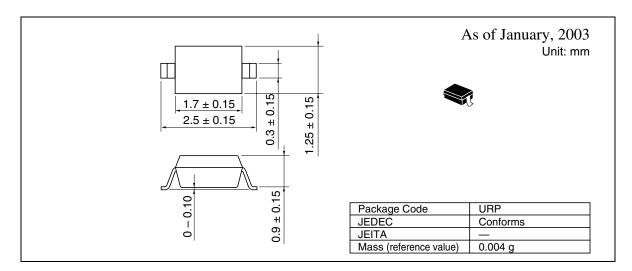
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	$V_R$	15.0	_	_	٧	I <sub>R</sub> = 10 μA
Reverse current	I <sub>R</sub>		_	100	nA	V <sub>R</sub> = 9 V
Capacitance	C <sub>1</sub>	50.0	_	85.0	pF	V <sub>R</sub> = 1 V, f = 1 MHz
	C <sub>3</sub>	16.1	_	27.3		V <sub>R</sub> = 3 V, f = 1 MHz
	C <sub>4.5</sub>	5.23	_	8.84		V <sub>R</sub> = 4.5 V, f = 1 MHz
Capacitance ratio	n	5.60	_	_	_	C <sub>1</sub> /C <sub>4.5</sub>
Figure of merit	Q	50	_	_	_	V <sub>R</sub> = 2.5 V, f = 10 MHz
ESD-Capability *1	_	80	_	_	V	C = 200 pF, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion;  $I_R \ge 100$ nA at  $V_R = 9$  V

#### **Main Characteristic**



## **Package Dimensions**



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